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With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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InGaP HBT 2.3 – 2.5 GHz Power Amplifier

PRODUCTION DATA SHEET

DESCRIPTION

The LX5514 is a power amplifier as a two-stage monolithic microwave current. integrated circuit (MMIC) with active bias and output pre-matching.

(HBT) IC Transistor

For 20dBm OFDM output power optimized for WLAN applications in (64QAM, 54Mbps), the PA provides a the 2.3 - 2.5GHz frequency range. low EVM (Error-Vector Magnitude) of The power amplifier is implemented 3.0%, and consumes 150mA total DC

The LX5514 is available in a standard 12-pin 2mm x 2mm micro-The device is manufactured with an lead package (MLP12L). The compact InGaP/GaAs Heterojunction Bipolar footprint, low profile, and thermal process capability of the MLP package make the (MOCVD). Power gain of 28dB is LX5514 an ideal solution for mediumobtained with a low quiescent current gain power amplifier requirements for IEEE 802.11b/g applications.

IMPORTANT: For the most current data, consult *MICROSEMI*'s website: http://www.microsemi.com

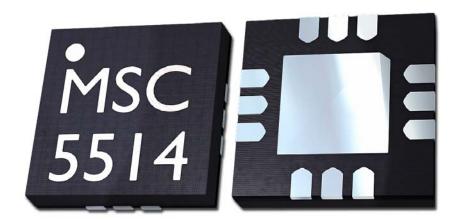
KEY FEATURES

- Advanced InGaP HBT
- 2.3 2.5GHz Operation
- Single-Polarity 3.3V Supply
- Quiescent Current 80mA
- Power Gain 28dB
- Total Current 150mA for P_{OUT}=20dBm OFDM
- EVM ~3 % 54Mbps / 64QAM
- Small Footprint: 2 x 2mm
- Low Profile: 0.46mm

APPLICATIONS

IEEE 802.11b/g

PRODUCT HIGHLIGHT



PACKAGE ORDER INFO

Plastic MLPO 12 pin

RoHS Compliant / Pb-free

LX5514LL

Note: Available in Tape & Reel. Append the letters "TR" to the part number. (i.e. LX5514LL-TR)



INFORMATION

Thank you for your interest in Microsemi® IPG products.

The full data sheet for this device contains proprietary information.

To obtain a copy, please contact your local Microsemi sales representative. The name of your local representative can be obtained at the following link http://www.microsemi.com/contact/contactfind.asp

or

Contact us directly by sending an email to:

IPGdatasheets@microsemi.com

Be sure to specify the data sheet you are requesting and include your company name and contact information and or vcard.

We look forward to hearing from you.